

T-43-25

**TOPAZ**  
SEMICONDUCTOR

**SD1107, SD1117**

## N-CHANNEL ENHANCEMENT-MODE D-MOS POWER FETS

### ORDERING INFORMATION

Configuration	Single	Quad	Single	Quad
Sorted Chips In Waffle Pack	SD1107CHP	—	SD1117CHP	—
TO-206AA (TO-18) Package	SD1107DD	—	SD1117DD	—
TO-205AF (TO-39) Package	SD1107HD	—	SD1117HD	—
TO-226AA (TO-92) Package	SD1107BD	—	SD1117BD	—
14-Pin Plastic DIP	—	SD1107N	—	SD1117N
Description	100V, 4.0 ohm		60V, 2.5 ohm	

### FEATURES

- Gate Standoff Voltage,  $\pm 40V$  min.
- Available in a wide variety of packages
- Low Capacitance
- Low ON Resistance
- P-Channel Complements Available, SD2107

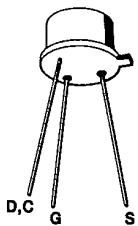
### APPLICATIONS

- High-Speed Pulse Amplifiers
- CMOS Logic to High-Current Interfaces
- High-Speed Switching
- Line Drivers

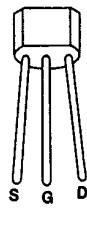
### PIN CONFIGURATIONS

TO-206AA  
(TO-18)

(See Package 1)

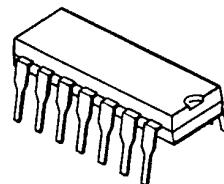
TO-205AF  
(TO-39)

(See Package 6)

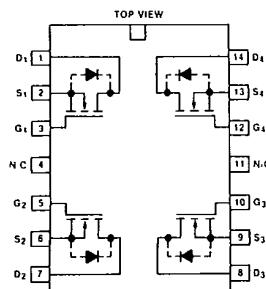
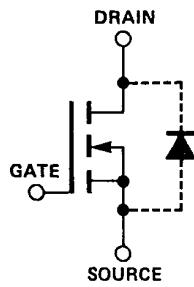
TO-226AA  
(TO-92)

(See Package 5)

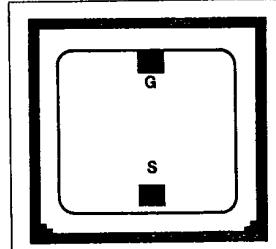
14-Pin Plastic DIP



(See Package 9)

SD1107N SD1117N  
4 Isolated Chips per Package

### CHIP CONFIGURATION

Dimensions: .054 x .051 x .020 in.  
Drain is backside contact.

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**SD1107, SD1117****ABSOLUTE MAXIMUM RATINGS Single Units ( $T_C = +25^\circ C$  unless otherwise noted)**

		Maximum Power Dissipation	
		$T_C = +100^\circ C$	$T_C = +25^\circ C$
Drain-Source Voltage SD1107	100V	HD, TO-39 Pkg.	2.75W
SD1117	60V	BD, TO-92 Pkg.	0.5W
Drain-Gate Voltage ( $V_{GS} = 1M\Omega$ ) SD1107	100V	DD, TO-18 Pkg.	0.7W
SD1117	60V		1.80W
Gate-Source Voltage	$\pm 40V$		
Continuous Drain Current		Linear Derating Factor	
		Junction to Ambient (mW/ $^\circ C$ )	Junction to Ambient (mW/ $^\circ C$ )
SD1107BD	$T_C = +100^\circ C$ 0.3A	HD, TO-39 Pkg. 0.4A	36.6 55
SD1107DD	$T_C = +100^\circ C$ 0.4A	BD, TO-92 Pkg. 0.5A	6.66 10.8
SD1107HD	$T_C = +100^\circ C$ 0.6A	DD, TO-18 Pkg. 1.0A	9.33 14.4
SD1117BD	$T_C = +100^\circ C$ 0.3A	Operating Junction and Storage Temperature Range	-55 $^\circ C$ to +150 $^\circ C$
SD1117DD	$T_C = +100^\circ C$ 0.4A		
SD1117HD	$T_C = +100^\circ C$ 0.8A	Lead Temperature (1/6" from mounting surface for 10 Sec)	+260 $^\circ C$
Peak Pulsed Drain Current	2.0A		

**ABSOLUTE MAXIMUM RATINGS Quad Units in 14-Pin Plastic DIP Package ( $T_C = +25^\circ C$  unless otherwise noted)**

		Peak Pulsed Drain Current ..... 2.0A	
		Continuous Device Dissipation	
		$T_C = +85^\circ C$	$T_C = +25^\circ C$
Drain-Source Voltage SD1107N	100V	Total Package .64W	2.0W
SD1117N	60V	Single Device .30W	1.0W
Drain-Gate Voltage ( $V_{GS} = 0$ ) SD1107N	100V		
SD1117N	60V	Total Package 10.6mW/ $^\circ C$	20mW/ $^\circ C$
Gate-Source Voltage	$\pm 0V$	Single Device 5.0mW/ $^\circ C$	10mW/ $^\circ C$
Continuous Drain Current		Operating Junction Temperature Range	-55 $^\circ C$ to +125 $^\circ C$
Total Package SD1107N	$T_C = +85^\circ C$ 0.3A	Storage Temperature Range	-55 $^\circ C$ to +125 $^\circ C$
SD1117N	0.4A		
Single Device SD1107N	$T_C = +85^\circ C$ 0.2A	Lead Temperature (1/16" from mounting surface for 10 Sec)	+260 $^\circ C$
SD1117N	0.3A		

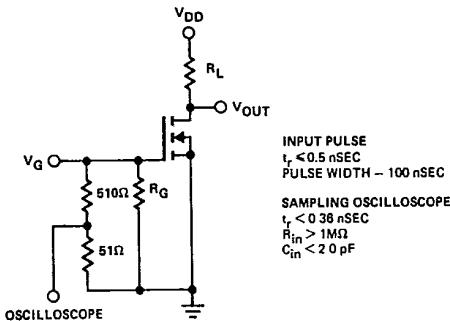
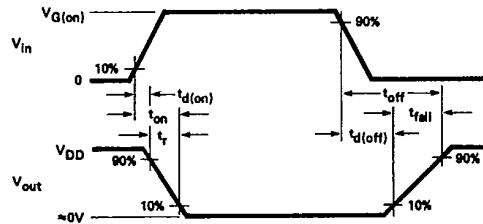
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**ELECTRICAL CHARACTERISTICS** ( $T_C = +25^\circ\text{C}$  unless otherwise noted)

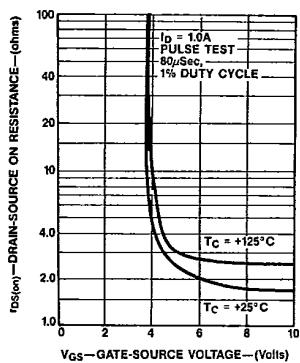
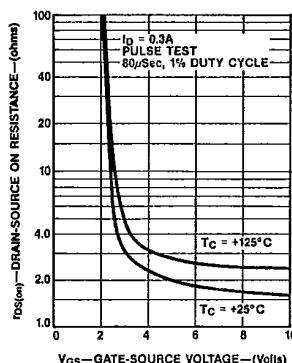
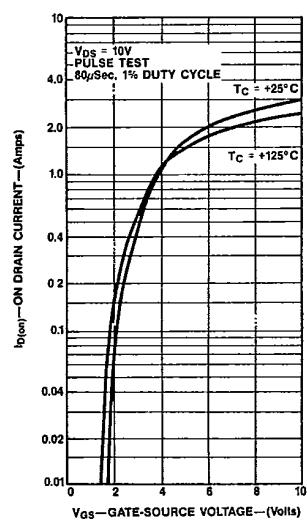
#	CHARACTERISTIC	SD1107			SD1117			UNIT	TEST CONDITIONS		
		MIN	Typ	MAX	MIN	Typ	MAX				
1	STATIC	BV <sub>DSS</sub>	Drain Source Breakdown Voltage	100	130		60	90	V	$I_D = 10\mu\text{A}, V_{GS} = 0$	
2		I <sub>GSSF</sub>	Gate Forward Leakage Current		.03	10		.03	10	nA	$V_{GS} = 20\text{V}$
3		I <sub>GSSR</sub>	Gate Reverse Leakage Current		-.03	-10		-.03	-10		$V_{GS} = -20\text{V}$
4		I <sub>DSS</sub>	Drain-Source OFF Leakage Current		2.0	200				nA	$V_{DS} = 80\text{V}$
5					2.0					$\mu\text{A}$	$V_{GS} = 0$
6							2.0	200	nA	V <sub>DS</sub> = 48V	$T_C = +125^\circ\text{C}$
7								2.0	$\mu\text{A}$		$V_{GS} = 0$
8		V <sub>GS(th)</sub>	Gate Source Threshold Voltage	0.8		2.0	0.8		2.0	V	$I_D = 1\text{mA}, V_{DS} = V_{GS}$
9		I <sub>D(ON)</sub>	ON Drain Current <sup>(1)</sup>	2.0	3.0		2.0	3.0		A	$V_{DS} = 10\text{V}, V_{GS} = 10\text{V}$
10		r <sub>D(on)</sub>	Drain-Source ON Resistance <sup>(1)</sup>		3.0	5.0		3.0	4.5	ohms	$V_{GS} = 5\text{V}$
11					8.5			7.6			$I_D = 0.3\text{A}$
12					1.9	4.0		1.9	2.5		$V_{GS} = 10\text{V}$
13					6.8			4.3			$I_D = 1.0\text{A}$
14	DYNAMIC	g <sub>fs</sub>	Forward Transconductance <sup>(1)</sup>	400	580		400	580		mS	$V_{DS} = 10\text{V}, I_D = 0.5\text{A}$ $f = 1\text{KHz}$
15		C <sub>iss</sub>	Common-Source Input Capacitance		80	100		80	100	pF	$V_{DS} = 25\text{V}, V_{GS} = 0$ $f = 1\text{MHz}$
16		C <sub>rss</sub>	Common-Source Reverse Transfer Capacitance		1.3	2.5		1.3	2.5		
17		C <sub>oss</sub>	Common-Source Output Capacitance		10.5	15		10.5	15		
18		t <sub>on</sub>	Turn-On Time		4.0	6.0		4.0	6.0	nSec	$V_{DD} = 25\text{V}, R_L = 25 \text{ ohms}$ $R_G = 51 \text{ ohms}, V_{G(on)} = 10\text{V}$
19		t <sub>off</sub>	Turn-Off Time		4.0	6.0		4.0	6.0		

Note 1: Pulse Test 80μSec, 1% Duty Cycle

**SWITCHING TIMES TEST CIRCUIT****TEST WAVEFORMS**

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TYPICAL PERFORMANCE CHARACTERISTICS ( $T_C = +25^\circ\text{C}$  unless otherwise noted)DRAIN-SOURCE ON RESISTANCE  
—vs—  
GATE-SOURCE VOLTAGEDRAIN-SOURCE ON RESISTANCE  
—vs—  
GATE-SOURCE VOLTAGEON DRAIN CURRENT  
—vs—  
GATE-SOURCE VOLTAGEFORWARD TRANSCONDUCTANCE  
—vs—  
ON DRAIN CURRENT